

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (currently amended) A silicon containing curing composition comprising:

at least one silicon containing polymer selected from the following components the group consisting of: component (A), component (B), and component (C), provided that the composition contains both the components (A) and (B) when the component (C) is absent; and the following

component (D) [[as]] being a catalyst, provided that the composition contains both the components (A) and (B) when the component (C) is absent.

wherein,

component (A) [[A]] is a silicon containing polymer, which comprises:

having at least one kind of a reactive group A' selected from the group consisting of Si-R¹, Si-O-R², and Si-R³-OCOC(R⁴)=CH₂, wherein R¹ and R² each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group[[;]], R³ represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group[[;]], and R⁴ represents hydrogen or a methyl group,

having an Si-O-Si bridge structure at at least one site thereof, and

containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less[[.]];

component (B) [[A]] is a silicon containing polymer,
which comprises:

having an Si-H group,

having an Si-O-Si bridge structure at at least one site thereof, and containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less[[.]];

component (C) [[A]] is a silicon containing polymer,
which comprises:

having at least one kind of a reactive group A' selected from the group consisting of Si-R¹, Si-O-R², and Si-R³-OCOC(R⁴)=CH₂, wherein R¹ and R² each represent an alkenyl group having 2 to 20 carbon atoms which may contain an alkylene group and/or an arylene group[[.]], R³ represents an alkylene group having 1 to 9 carbon atoms and/or an arylene group[[.]], and R⁴ represents hydrogen or a methyl group, and

an Si-H group,

having an Si-O-Si bridge structure at at least one site thereof, and

containing 20% by weight or less of a component whose weight average molecular weight is 1000 or less[[.]];

component (D) [[A]] is a platinum-based catalyst as a catalyst for curing reaction.

2. (original) The silicon containing curing composition according to claim 1, wherein the total aryl group and arylene group content of the total silicon containing polymers as components (A), (B), and (C) is 0.1% to 50% by weight.

3. (currently amended) The silicon containing curing composition according to claim 1, ~~which further comprises comprising~~ a metal oxide fine powder as component (E).

4. (previously presented) A cured product obtained by heat curing the silicon containing curing composition according to claim 1.

5. (currently amended) The silicon containing curing composition according to claim 2, ~~which further comprises comprising~~ a metal oxide fine powder as component (E).